L Number	Hits	Search Text	DB	Time stamp
1	165	(waffle adj pack) or (matrix adj tray)	USPAT;	2002/10/23 08:28
	,		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	117		USPAT;	2002/10/18 13:58
		die) and underfill	US-PGPUB;	
	1		EPO; JPO; DERWENT;	
			IBM TDB	
_	43	interposer near8 (solder adj ball or solder	USPAT;	2002/10/18 14:01
		adj bump) and (semiconductor near2 ic or	US-PGPUB;	, ,
		die) and underfill	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	59	interposer near8 (solder adj ball or solder adj bump) and (semiconductor near2 ic or	USPAT;	2002/10/18 14:31
	,	die) and interposer near4 (underfill or	US-PGPUB; EPO; JPO;	
	ļ	adhesive or dielectric)	DERWENT;	
		,	IBM TDB	
-	0	interposer near2 (adhesive or underfill)	USPAT;	2002/10/18 14:32
		near7 (wiring near board)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
_	64	interpoper pears (adhesive or underfill) and	IBM_TDB	2002/30/30 16 00
_	04	interposer near8 (adhesive or underfill) and (adhesive or underfill) near4 (aperture or	USPAT; US-PGPUB;	2002/10/18 16:00
		hole or via)	EPO; JPO;	
	į		DERWENT;	
			IBM_TDB	
-	0		USPAT;	2002/10/18 16:04
	, ,	adhesive or underfill or dielectric) near4	US-PGPUB;	
		(low near (temperature or T) near2 (drying or processing))	EPO; JPO; DERWENT;	
		or processing, ,	IBM TDB	
-	0	(die or ic or integrated adj circuit) near4	USPAT;	2002/10/18 16:07
		(printed adj circuit adj board or printed	US-PGPUB;	. ,
	Į į	adj wiring adj board or pcb or pwb) and	EPO; JPO;	
		(bonding or bond or adhesive or underfill or	DERWENT;	
		dielectric) near4 (low near (temperature or T) near2 (drying or processing))	IBM_TDB	
_	49	(die or ic or integrated adj circuit or	USPAT;	2002/10/18 16:26
	,	interposer) near4 (printed adj circuit adj	US-PGPUB;	2002, 10, 10 10.20
	, !	board or printed adj wiring adj board or pcb	EPO; JPO;	
		or pwb) and (bonding or bond or adhesive or	DERWENT;	
		underfill or dielectric) near5 (abrading or	IBM_TDB	
		abrasion or abrade or chemical adj mechanical adj polishing or cmp or grinding		
		or mechanical adj polishing or camp or grinding or mechanical adj polishing or laser adj		
		ablation)		
-	1827	(integrated adj circuit or ic or die or	USPAT;	2002/10/18 16:29
ı		printed adj circuit adj board or pcb) and	US-PGPUB;	
		interposer	EPO; JPO;	
			DERWENT;	
_	830	(integrated add direction on in on dia)	IBM_TDB	2002/10/20 16 22
	0.30	(integrated adj circuit or ic or die) and (printed adj circuit adj board or printed	USPAT; US-PGPUB;	2002/10/18 16:30
		adj wiring adj board or pcb) and interposer	EPO; JPO;	
			DERWENT;	
		<b>,</b>	IBM_TDB	
~	632	((integrated adj circuit or ic or die) and	USPAT;	2002/10/18 16:32
	, ,	(printed adj circuit adj board or printed	US-PGPUB;	
	, ,	adj wiring adj board or pcb) and interposer)	EPO; JPO;	
		and (bonding or bond)	DERWENT;	
			IBM_TDB	

-	115		USPAT;	2002/10/18 16:34
		(printed adj circuit adj board or printed	US-PGPUB;	
		adj wiring adj board or pcb) and interposer)	EPO; JPO;	
		and (bonding or bond)) and (layer or dielectric or adhesive or solder or	DERWENT;	
		underfill) near3 (bottom or below or top or	IBM_TDB	
		above or between) near3 interposer		
_	28	(die or ic or integrated adj circuit or	USPAT;	2002/10/21 13:49
		semiconductor adj device) and (interposer or	US-PGPUB;	2002, 20, 22 23.13
		interposing or interpose) and (wiring adj	EPO; JPO;	
		board or circuit adj board or pwb or pcb)	DERWENT;	
		and (underfill or underfilling or flux or	IBM_TDB	
		adhesive) near5 (interposer or interposing	_	
į		or interpose) near5 (solder or electrode)		
-	351	(interposer) near5 (bond or connect or	USPAT;	2002/10/21 13:53
		bonding or connecting or adhering or	US-PGPUB;	
		adhesive or bonded or connected or adhered	EPO; JPO;	
		or underfill or flux or underfilled or underfilling) near5 (circuit adj board or	DERWENT;	
		wiring adj board or pcb or pwb or substrate)	IBM_TDB	
_	106	((interposer) near5 (bond or connect or	USPAT;	2002/10/21 13:55
		bonding or connecting or adhering or	US-PGPUB;	2002/10/21 13.33
		adhesive or bonded or connected or adhered	EPO; JPO;	
		or underfill or flux or underfilled or	DERWENT;	
		underfilling) near5 (circuit adj board or	IBM_TDB	
		wiring adj board or pcb or pwb or	_	
		substrate)) and (chemical adj mechanical adj		
		polishing or cmp or abrading or grinding or		
		mechanical adj polishing or laser or		
	8	ablation) (low near2 (temperature or temp or t) near3	110000	2000/10/00 11 50
. –	•	(drying or curing or dehydrating)) and flip	USPAT; US-PGPUB;	2002/10/22 11:50
		adj chip and (underfill or encapsulant or	EPO; JPO;	<b>;</b>
ŀ		flux)	DERWENT;	
		,	IBM TDB	
_	18340	curing near4 (drying or dehydrating or	USPAT;	2002/10/22 11:52
		water)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	12383	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/10/22 11:54
		water)	US-PGPUB;	
			EPO; JPO; DERWENT;	
		·	IBM TDB	
_	1	interposer near6 (singulate or singulated or	USPAT;	2002/10/22 11:56
	_	dicing) near10 (carrier or tape or reel or	US-PGPUB;	= = = = = = = = = = = = = = = = = = =
	ŀ	waffle or matrix)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	9	interposer near6 (singulate or singulated or	USPAT;	2002/10/22 12:08
		dicing) and (carrier or tape or reel or	US-PGPUB;	
		waffle or matrix or panel)	EPO; JPO;	
			DERWENT;	
_	74	singulate or singulating or singulated or	IBM_TDB USPAT;	2002/10/22 12:42
	/*	singulation) near6 (circuit adj board or	US-PGPUB;	2002/10/22 12:43
		wiring adj board or pcb or pwb)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	46	((singulate or singulating or singulated or	USPAT;	2002/10/22 12:44
		singulation) near6 (circuit adj board or	US-PGPUB;	
		wiring adj board or pcb or pwb)) and	EPO; JPO;	
		(carrier or tape or reel or waffle or	DERWENT;	
		matrix)	IBM_TDB	